

3.0Amp Schottky Barrier Rectifiers

Reverse Voltage 70V to 100V Forward Current 3A

SB370 thru SB3B0

Features

- Metal-semiconductor junction with guard ring.
- Epitaxial construction
- Low forward voltage drop
- High current capability

Mechanical Data

- Case : Molded plastic DO-201AD
- Epoxy : UL94V-0 rate flame retardant
- Terminals: Solderable per MIL-STD-202 method 208 guaranteed
- Polarity: Color band denotes cathode end.
- Mounting Position : Any.
- Weight: 0.041 oz., 1.15 gram

Outline

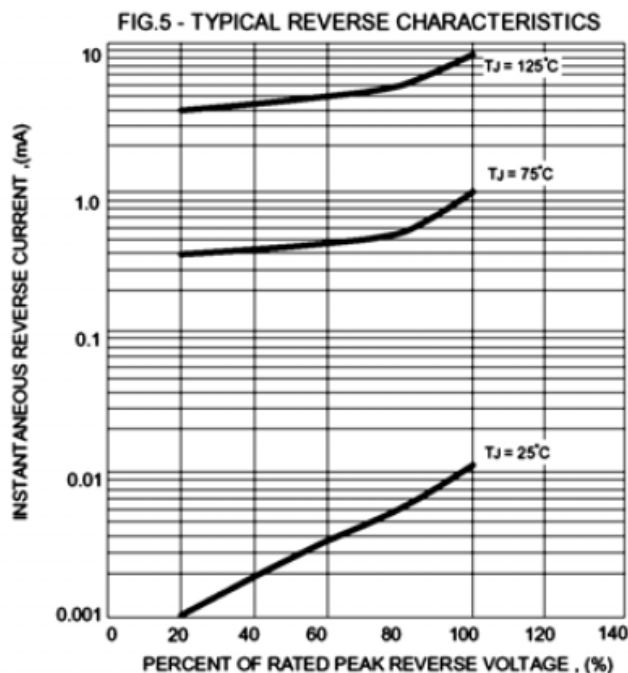
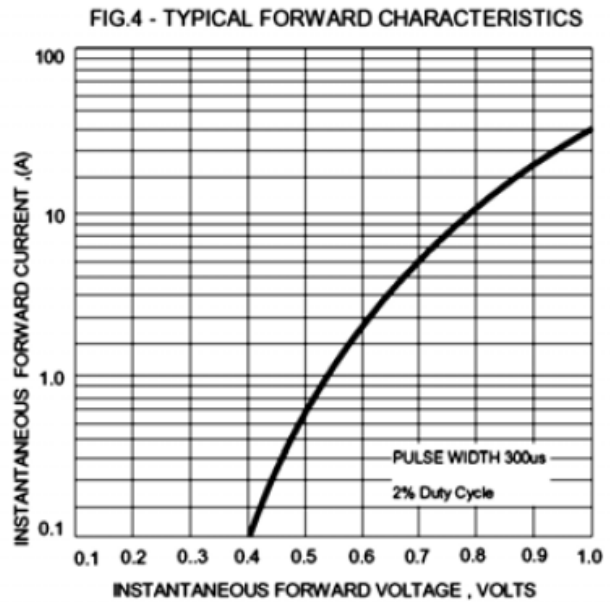
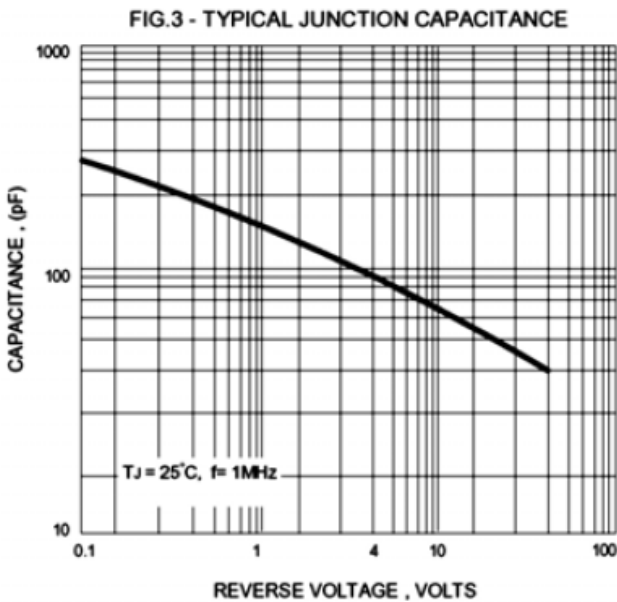
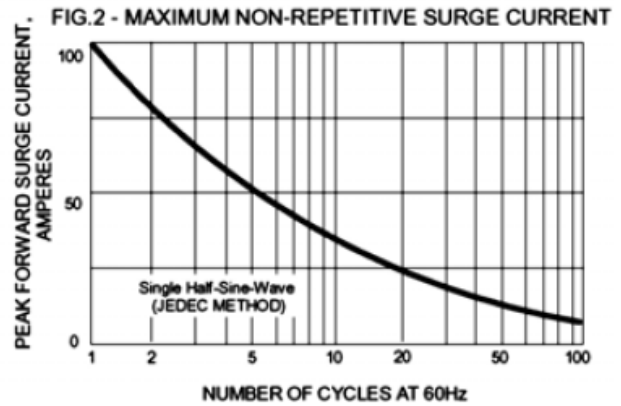
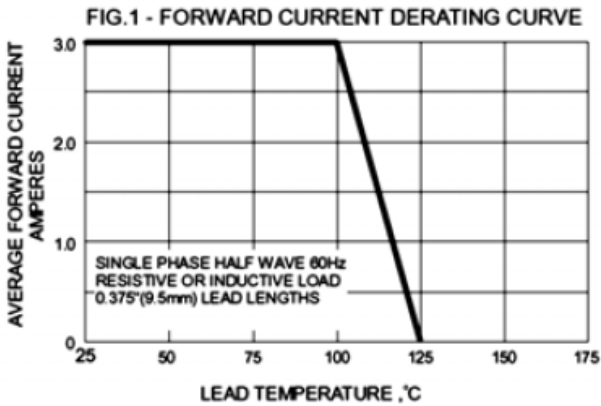


Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%)

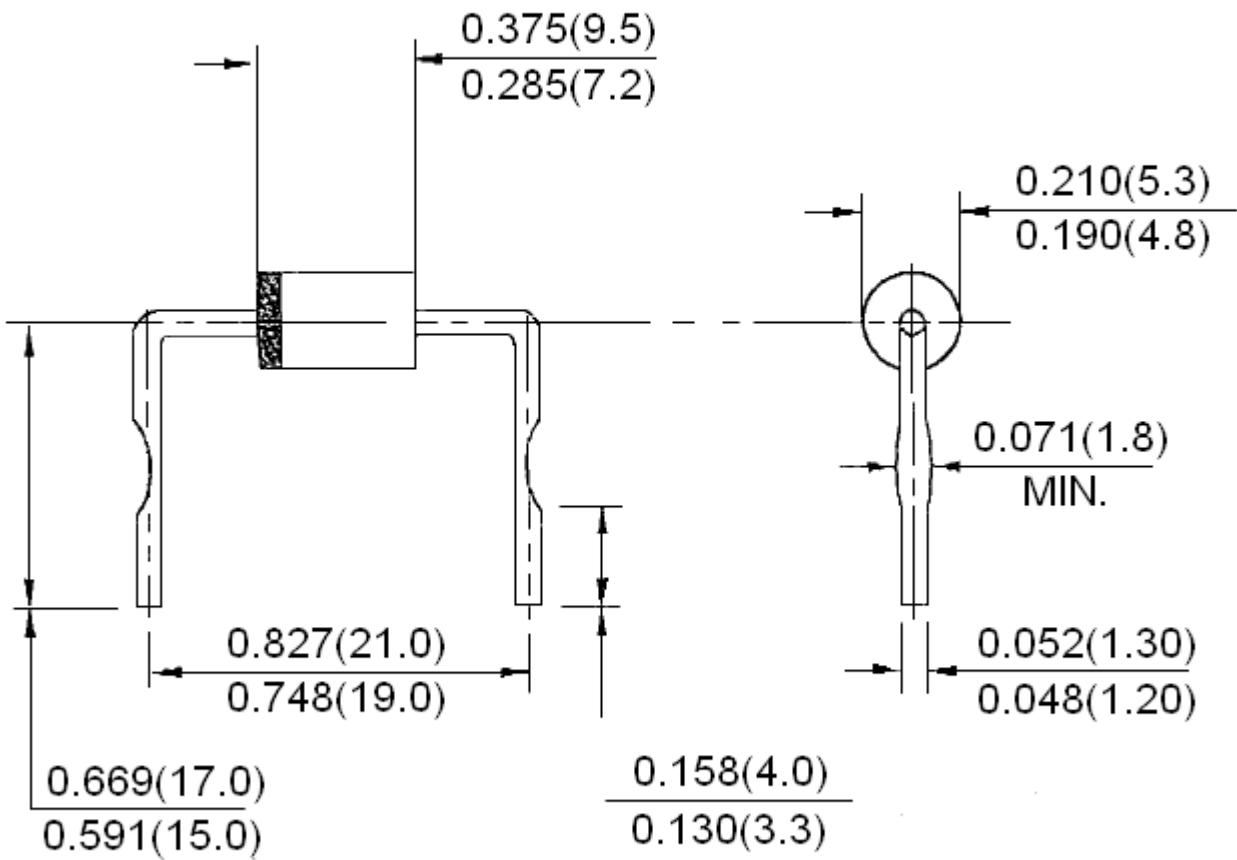
Parameter	Symbol	Type				Units
		SB370	SB380	SB390	SB3B0	
Maximum repetitive peak reverse voltage	V _{RRM}	70	80	90	100	V
Maximum RMS voltage	V _{RMS}	49	56	63	70	V
Maximum DC blocking voltage	V _{DC}	70	80	90	100	V
Maximum forward voltage at I _F =3A	V _F	0.79				V
		0.69				
Maximum average forward rectified current @ 0.375"(9.5mm) lead length, T _L =100 °C	I _{F(AV)}	3				A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I _{FSM}	100				A
Maximum DC reverse current at rated DC blocking voltage	I _R	0.5				mA
		20				
Typical thermal resistance, junction to lead	R _{θJL}	25				°C/W
Typical junction capacitance @ f=1MHz and applied 4V DC reverse voltage	C _J	90				pF
Operating junction temperature range	T _J	-55 ~ +125				°C
Storage temperature range	T _{STG}	-55 ~ +150				°C

Characteristic Curves



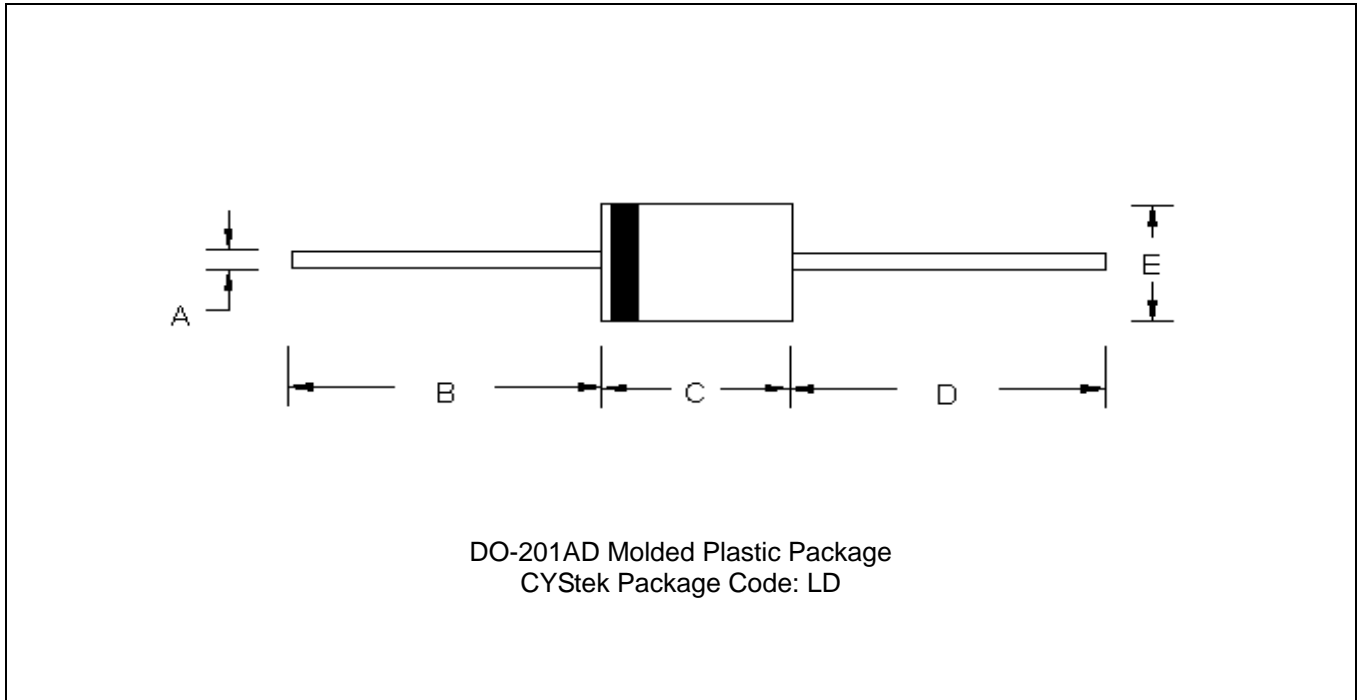
Forming Dimension

C542-2



Dimensions in inches(millimeters)

DO-201AD Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	φ0.048	φ0.052	φ1.20	φ1.30	D	1.000	-	25.40	-
B	1.000	-	25.40	-	E	φ0.190	φ0.220	φ4.80	φ5.60
C	0.285	0.375	7.20	9.50					

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Mold Compound : Epoxy resin family, flammability solid burning class: UL94V-0

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